Power MOSFET

40 V, 5.6 m Ω , 69 A, Single N-Channel

Features

- Small Footprint (3.3 x 3.3 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- NVTFWS005N04C Wettable Flanks Product
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parar	Symbol	Value	Unit		
Drain-to-Source Voltage			V_{DSS}	40	٧
Gate-to-Source Voltage	Э		V _{GS}	±20	٧
Continuous Drain		T _C = 25°C	I _D	69	Α
Current R _{θJC} (Notes 1, 2, 3, 4)	Steady	T _C = 100°C		39	
Power Dissipation	State	T _C = 25°C	P_{D}	50	W
R _{θJC} (Notes 1, 2, 3)		T _C = 100°C	1	16	
Continuous Drain		T _A = 25°C	I _D	17	Α
Current R _{0JA} (Notes 1, 3, 4)	Steady	T _A = 100°C		12	
Power Dissipation	State	T _A = 25°C	P _D	3.1	W
R _{θJA} (Notes 1, 3)		T _A = 100°C	1	1.6	
Pulsed Drain Current	$T_A = 25$	$T_A = 25^{\circ}C, t_p = 10 \mu s$		297	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			I _S	42	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 4.6 A)			E _{AS}	103	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS (Note 1)

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 3)	$R_{\theta JC}$	3.0	°C/W
Junction-to-Ambient - Steady State (Note 3)	$R_{\theta JA}$	47.7	

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Psi (Ψ) is used as required per JESD51-12 for packages in which substantially less than 100% of the heat flows to single case surface.
- 3. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- Continuous DC current rating. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

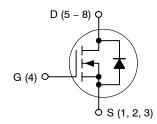


ON Semiconductor®

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V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX		
40 V	5.6 m Ω @ 10 V	69 A		

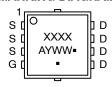
N-Channel





WDFN8 (μ8FL) CASE 511AB

MARKING DIAGRAM



XXXX = Specific Device Code A = Assembly Location

Y = Year WW = Work Week • = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•	•			•	•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		40	_	_	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	$V_{CS} = 0 \text{ V}$ $T_J = 25^{\circ}\text{C}$		_	10	μΑ
		$V_{DS} = 40 \text{ V}$	T _J = 125°C	-	_	250	
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{G}$	_S = 20 V	-	-	100	nA
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D}$	= 40 μΑ	2.5	_	3.5	V
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _E	₎ = 35 A	-	4.7	5.6	mΩ
Forward Transconductance	9FS	V _{DS} = 15 V, I _E	₎ = 35 A	-	53	-	S
CHARGES AND CAPACITANCES	•				•	•	
Input Capacitance	C _{iss}			-	1000	-	pF
Output Capacitance	C _{oss}	V _{GS} = 0 V, f = V _{DS} = 25	1.0 MHz,	-	530	-	-
Reverse Transfer Capacitance	C _{rss}	VDS - 20	v _{DS} = 25 v		22	-	
Threshold Gate Charge	Q _{G(TH)}			-	3.2	-	nC
Gate-to-Source Charge	Q _{GS}	V _{GS} = 10 V, V _{DS} = 3	V _{GS} = 10 V, V _{DS} = 32 V, I _D = 35 A		5.7	-	-
Gate-to-Drain Charge	Q _{GD}			-	2.7	-	
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 3	32 V, I _D = 35 A	-	16	-	nC
SWITCHING CHARACTERISTICS (No	te 6)	•			•	•	
Turn-On Delay Time	t _{d(on)}			-	11	-	ns
Rise Time	t _r	V _{GS} = 10 V, V _D	e = 32 V.	-	72	-	-
Turn-Off Delay Time	t _{d(off)}	I _D = 35	Ä	-	24	-	
Fall Time	t _f			-	8	-	-
DRAIN-SOURCE DIODE CHARACTER	RISTICS	•			•	•	
Forward Diode Voltage	V_{SD}	$V_{GS} = 0 \text{ V},$ $T_{J} = 25^{\circ}\text{C}$		-	0.87	1.2	V
		I _S = 35 A	T _J = 125°C	-	0.75	-	1
Reverse Recovery Time	t _{RR}		•	-	36	-	ns
Charge Time	t _a	V_{GS} = 0 V, dl_S/dt = 100 A/ μ s, l_S = 35 A		-	17	-	1
Discharge Time	t _b			-	18	-	1
Reverse Recovery Charge	Q _{RR}			-	16	-	nC

^{5.} Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
6. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

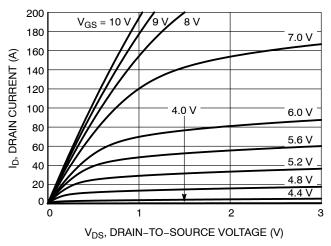


Figure 1. On-Region Characteristics

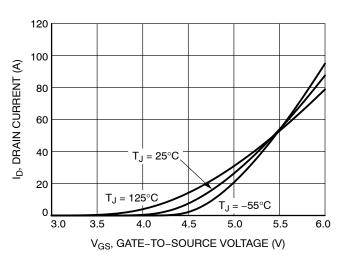


Figure 2. Transfer Characteristics

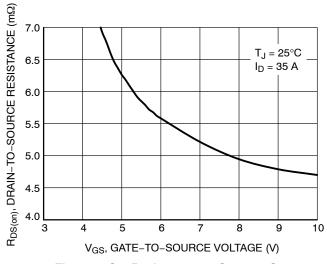


Figure 3. On-Resistance vs. Gate-to-Source Voltage

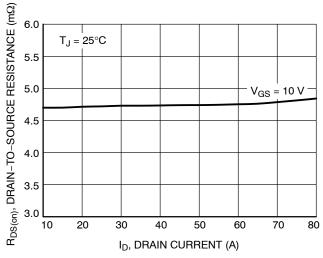


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

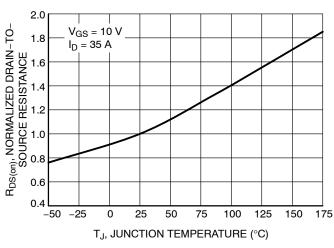


Figure 5. On–Resistance Variation with Temperature

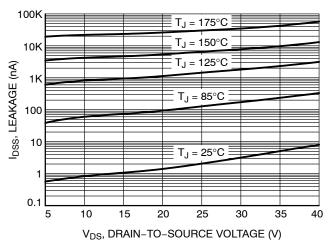


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

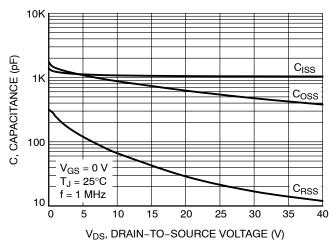


Figure 7. Capacitance Variation

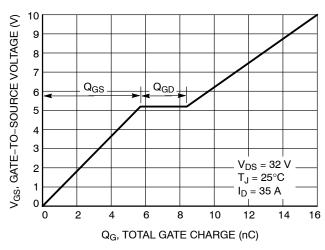


Figure 8. Gate-to-Source Voltage vs. Total Charge

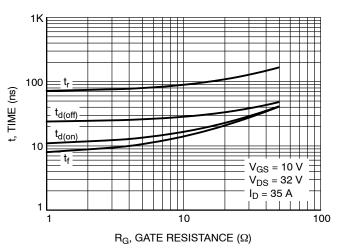


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

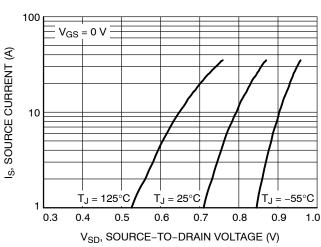


Figure 10. Diode Forward Voltage vs. Current

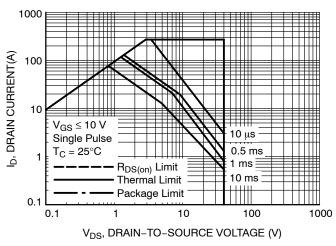


Figure 11. Maximum Rated Forward Biased Safe Operating Area

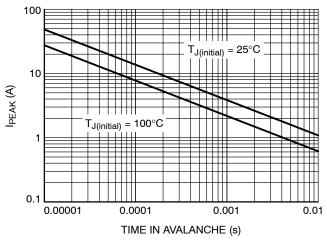


Figure 12. I_{PEAK} vs. Time in Avalanche

TYPICAL CHARACTERISTICS

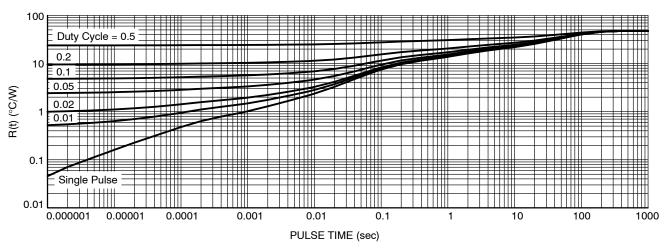


Figure 13. Thermal Characteristics

DEVICE ORDERING INFORMATION

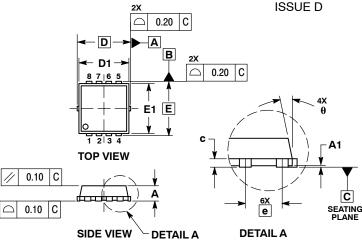
Device	Marking	Package	Shipping [†]	
NVTFS005N04CTAG	05NC	WDFN8 (Pb-Free)	1500 / Tape & Reel	
NVTFWS005N04CTAG	05NW	WDFN8 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

WDFN8 3.3x3.3, 0.65P

CASE 511AB



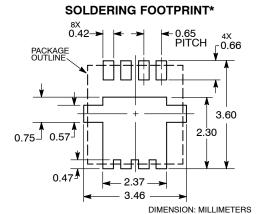
NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.70	0.75	0.80	0.028	0.030	0.031	
A1	0.00		0.05	0.000		0.002	
b	0.23	0.30	0.40	0.009	0.012	0.016	
С	0.15	0.20	0.25	0.006	0.008	0.010	
D		3.30 BSC		0.130 BSC			
D1	2.95	3.05	3.15	0.116	0.120	0.124	
D2	1.98	2.11	2.24	0.078	0.083	0.088	
E		3.30 BSC		C	.130 BSC	;	
E1	2.95	3.05	3.15	0.116	0.120	0.124	
E2	1.47	1.60	1.73	0.058	0.063	0.068	
E3	0.23	0.30	0.40	0.009	0.012	0.016	
е	0.65 BSC			0.026 BSC			
G	0.30	0.41	0.51	0.012	0.016	0.020	
K	0.65	0.80	0.95	0.026	0.032	0.037	
L	0.30	0.43	0.56	0.012	0.017	0.022	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
М	1.40	1.50	1.60	0.055	0.059	0.063	
θ	0 °		12 °	0 °		12 °	

0.10 С A B \oplus С 0.05 e/2 E3 D2 G **BOTTOM VIEW**



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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